Claims

[c1] 1.A semiconductor package comprising:
a chip carrier including a grounded pad on a first side of said chip carrier;
a semiconductor chip coupled to said first side of said chip carrier;
a conductive lid thermally coupled to said semiconductor chip; and
a conductive structure electrically coupled to said grounded pad and to said conductive lid.

[c2] 2.The semiconductor package according to claim 1 wherein a solder connects said conductive structure and said grounded pad.

[c3] 3.The semiconductor package according to claim 1 wherein said conductive structure is electrically coupled to said grounded pad with an electrically conductive adhesive material.

[c4] 4.The semiconductor package according to claim 1 wherein said conductive structure is electrically coupled to said conductive lid with an electrically conductive adhesive material.

[c5] 5.The semiconductor package according to claim 1 wherein said conductive structure is coupled to said chip carrier using an electrically insulative adhesive material.

[c6] 6.The semiconductor package according to claim 1 wherein said conductive structure is coupled to said chip carrier using a thermally conductive adhesive material.

[c7] 7.The semiconductor package according to claim 1 wherein said conductive structure comprises a spring.

[c8] 8.The semiconductor package according to claim 1 wherein said conductive structure comprises a block.

[c9] 9.The semiconductor package according to claim 1 wherein said block comprises a surface mount technology (SMT) discrete component.

[c10] 10.The semiconductor package according to claim 1 wherein
a solder couples said conductive structure to said grounded pad;
an electrically conductive adhesive material couples said conductive structure to said conductive lid; and
an electrically insulative adhesive material couples said conductive structure to the chip carrier.

[c11] 11.The semiconductor package according to claim 10

wherein said conductive structure comprises a conductive spring.

[c12] 12.The semiconductor package according to claim 10 wherein said conductive structure comprises a block.

[c13] 13.The semiconductor package according to claim 10 wherein said conductive structure comprises a surface mount technology (SMT) discrete component.

[c14] 14.A method for manufacturing a semiconductor package, the semiconductor package including a chip carrier having a grounded pad, said method comprising the steps of:
applying a first electrically conductive adhesive material on said grounded pad;
providing a conductive structure coupled to said first electrically conductive adhesive material;
providing a semiconductor chip on said chip carrier;
applying a second electrically conductive adhesive material on said conductive structure;
applying electrically insulative adhesive material on said semiconductor chip; and
providing a conductive lid coupled to said second electrically conductive adhesive material and said electrically insulative adhesive material.

[c15] 15.The method according to claim 14 wherein said first electrically conductive adhesive material comprises solder.

[c16] 16.The method according to claim 14 wherein said conductive structure comprises a conductive spring.

[c17] 17.The method according to claim 14 wherein said conductive structure comprises a surface mount technology (SMT) discrete component.

[c18] 18.The method according to claim 14 wherein said conductive structure comprises a conductive block.

[c19] 19.The method according to claim 14 wherein the step of providing said conductive structure coupled to said first electrically conductive adhesive material comprises picking said conductive structure from a first location and placing said conductive structure on said first electrically conductive adhesive material.

[c20] 20.The method according to claim 14 wherein the step of providing said semiconductor chip on said chip carrier comprises picking said semiconductor chip from a second location and placing said semiconductor chip on said chip carrier.